



# SOT616-3

plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm

4 March 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN24
<b>Package type industry code</b>	HVQFN24
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	19-2-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	3.9	-	4	4.1	mm
E	package width	3.9	-	4	4.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A <sub>2</sub>	package height	[tbd]	-	0.85	[tbd]	mm
e	nominal pitch	-	-	[tbd]	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	24	-	

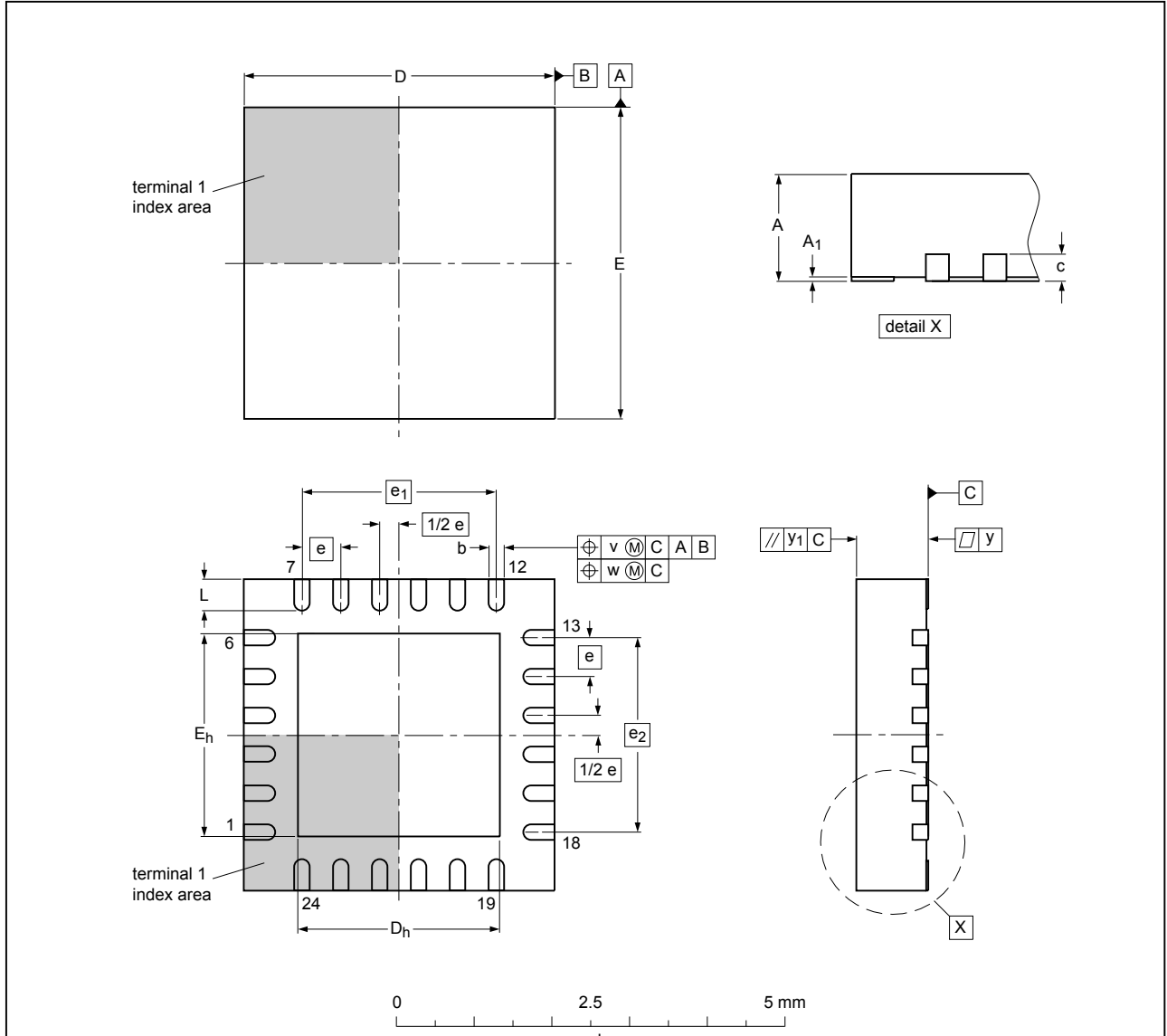


plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm

## 2. Package outline

HVQFN24: plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm

SOT616-3A



Dimensions (mm are the original dimensions)

Unit <sup>(1)</sup>	A <sup>(1)</sup>	A <sub>1</sub>	b	c	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
max	1	0.05	0.30		4.1	2.75	4.1	2.75				0.5				
nom				0.2					0.5	2.5	2.5		0.1	0.05	0.05	0.1
min		0.00	0.18		3.9	2.45	3.9	2.45				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot616-3a\_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT616-3A		MO-220				<del>16-02-16</del> 16-02-17

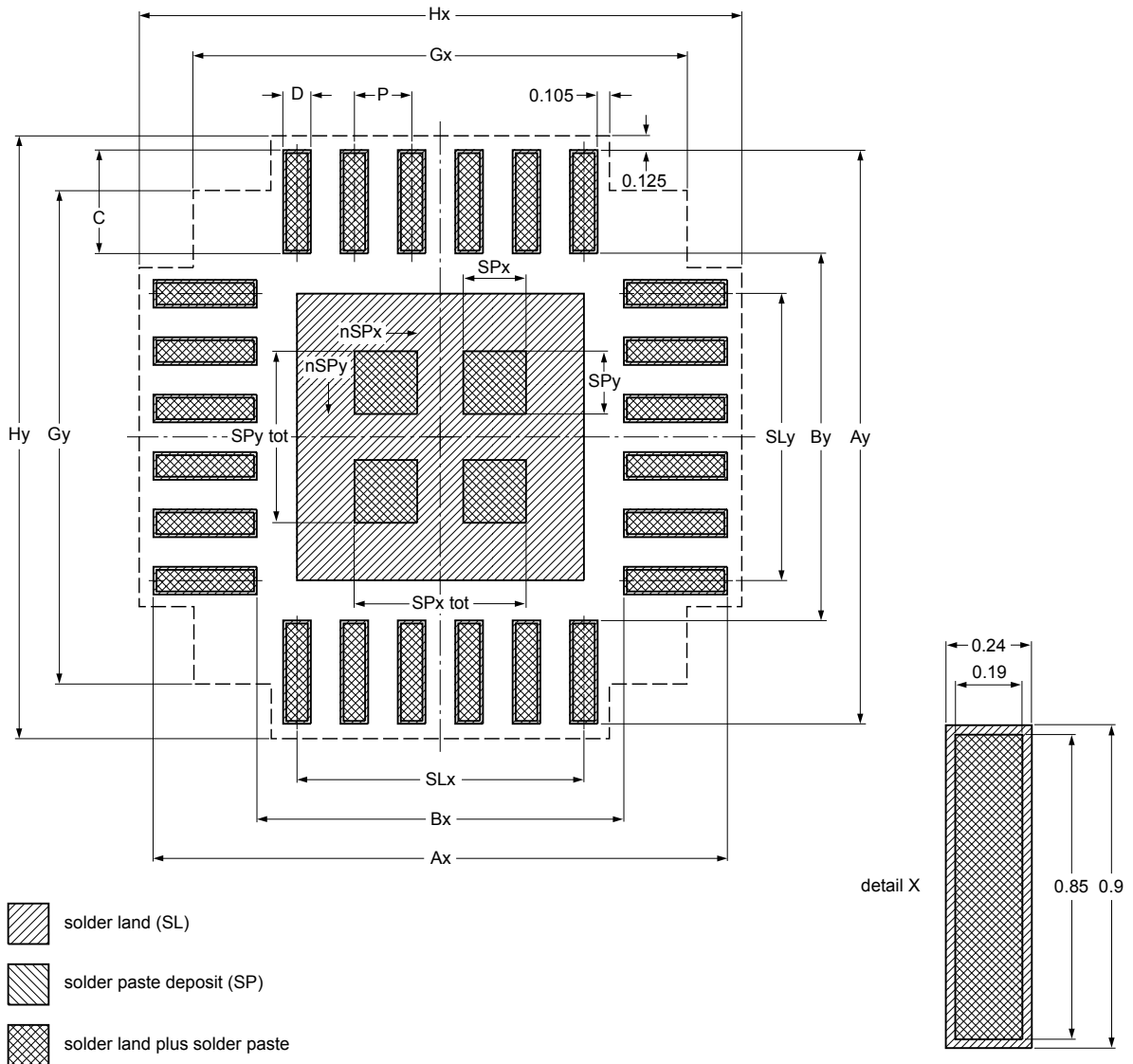
Fig. 1. Package outline HVQFN24 (SOT616-3)

plastic thermal enhanced very thin quad flat package; no leads; 24 terminals; body 4 x 4 x 0.85 mm

### 3. Soldering

Footprint information for reflow soldering of HVQFN24 package

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----- occupied area  
 recommend stencil thickness: 0.1 mm

Dimensions in mm

P	Ax	Ay	Bx	By	SLx	SLy	SPx	SPy	SPx tot	SPy tot	C	D	nSPx	nSPy	Gx	Gy
0.50	5.00	5.00	3.20	3.20	2.50	2.50	0.55	0.55	1.50	1.50	0.90	0.24	2	2	4.30	4.30

Issue date ~~09-06-15~~  
 14-06-12

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Fig. 2. Reflow soldering footprint for HVQFN24 (SOT616-3)

plastic thermal enhanced very thin quad flat  
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## 4. Legal information

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)  
Date of release: 4 March 2016

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